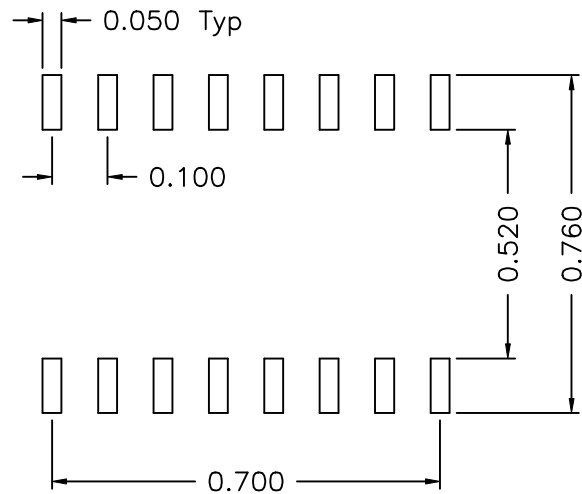
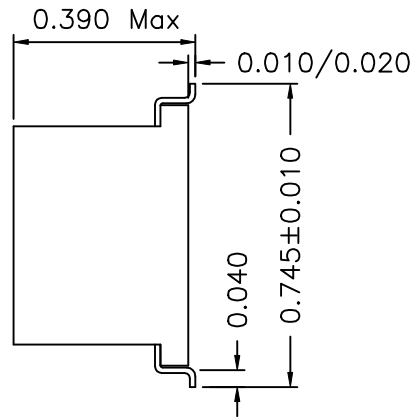
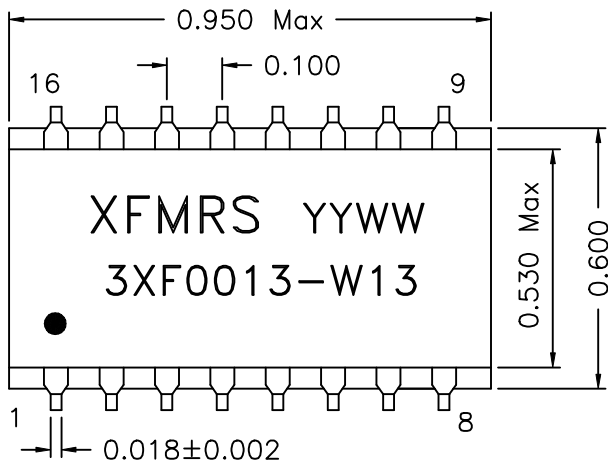


## 1. Dimensions:



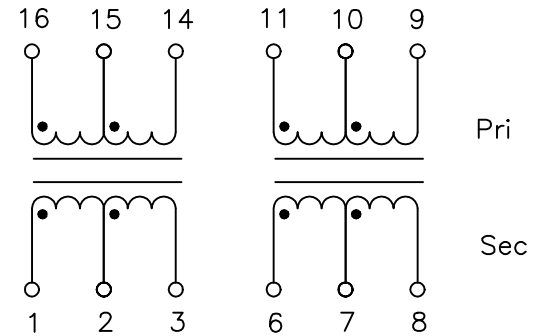
SUGGESTED PCB LAYOUT

### Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible

DOC. REV A/2

## 2. Schematic:



## 2. Electrical Specifications @25°C

TURN RATIO: P16-15-14:P1-2-3 1CT:1.41CT±2%  
 TURN RATIO: P11-10-9:P6-7-8 1CT:1.41CT±2%  
 OCL: P16-14,P11-9 1.2 mH Min @100KHz 0.1V  
 LL: P16-14 0.8uH Max @100KHz 0.1V  
 LL: P11-9 0.8uH Max @100KHz 0.1V  
 CW/W: P1-16 25pF Max @100KHz 0.1V  
 CW/W: P6-11 25pF Max @100KHz 0.1V  
 DCR: P1-3,P6-8 0.70 Ohms Max  
 DCR: P16-14, P11-9 0.50 Ohms Max  
 HIPOT: 3000Vrms

<b>XFMRS Inc</b>	Title: Dual T1/CEPT/ISDN-Pri Reinforced Ins 3KV SM	
	P/N: 3XF0013-W13	REV. A
	DWN. 李清儿	Jun-11-99
	CHK. 孙小悦	Jun-11-99
APP. Joe Huff	Jun-11-99	